



150V N-Channel MOSFETs

General Description

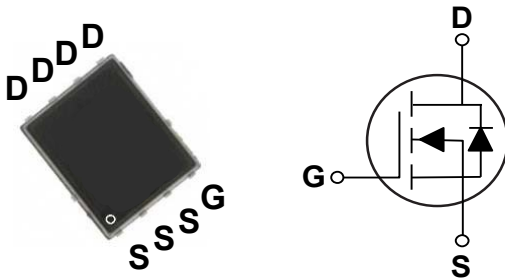
These N-Channel enhancement mode power field effect transistors are using SGT MOSFET technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV _{DSS}	R _{DS(ON)}	I _D
150 V	11.5 mΩ	100 A

Features

- R_{DS(ON)} ≤ 11.5mΩ@V_{GS}=10V
- Fast Switching
- Improved dv/dt Capability
- Green Device Available

PPAK5X6 Pin Configuration



Applications

- Power Management Switches
- DC/DC Converter
- Synchronous Rectification in SMPS

Absolute Maximum Ratings T_J=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _{DS}	Drain-Source Voltage	150	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Drain Current - Continuous (T _C =25°C)	100	A
I _{DM}	Drain Current - Pulsed (NOTE 1)	400	A
EAS	Single Pulse Avalanche Energy (NOTE 2)	80	mJ
P _D	Power Dissipation (T _C =25°C)	215	W
T _J	Operating Junction Temperature Range	-55 to 150	°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
Marking Code		NP012A	

Thermal Characteristics

Symbol	Parameter	Value	Unit
R _{θJA}	Thermal Resistance Junction to Ambient	54	°C/W
R _{θJC}	Thermal Resistance Junction to Case	0.58	°C/W



Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	150	---	---	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =150V, V _{GS} =0V	---	---	1	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =20A	---	---	11.5	mΩ
		V _{GS} =4.5V, I _D =10A	---	---	16	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1	---	3	V

Dynamic and switching Characteristics (NOTE 4)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q _g	Total Gate Charge	V _{DS} =75V, V _{GS} =10V, I _D =20A	---	43	---	nC
Q _{gs}	Gate-Source Charge		---	14.5	---	
Q _{gd}	Gate-Drain Charge		---	18	---	
T _{d(on)}	Turn-On Delay Time	V _{DS} =75V, V _{GS} =10V, R _G =10Ω, I _D =20A	---	17.5	---	nS
T _r	Rise Time		---	7.9	---	
T _{d(off)}	Turn-Off Delay Time		---	28	---	
T _f	Fall Time		---	10.3	---	
C _{iss}	Input Capacitance	V _{DS} =75V, V _{GS} =0V, F=1MHz	---	3420	---	pF
C _{oss}	Output Capacitance		---	262	---	
C _{rss}	Reverse Transfer Capacitance		---	9.2	---	
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	---	2.2	---	Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V, Force Current	---	---	100	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =20A	---	---	1.2	V
t _{rr}	Body Diode Reverse Recovery Time	V _R =75V, I _F =20A,	---	81	---	nS
Q _{rr}	Body Diode Reverse Recovery Charge	di/dt=100A/us	---	162	---	nC

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The EAS data shows Max. rating. The test condition is V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=40A.
3. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
4. This value is guaranteed by design hence it is not included in the production test.



Characteristics Curves

FIG. 1-Transfer Characteristics

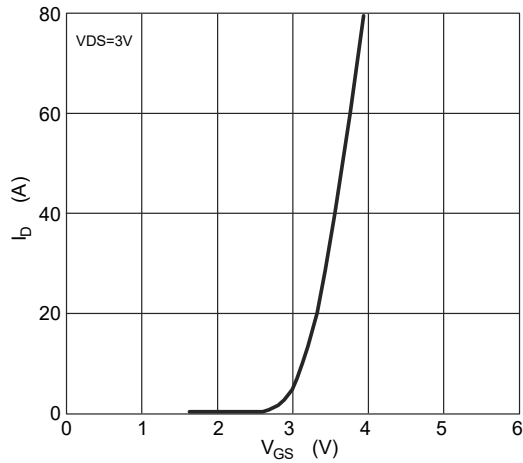


FIG. 2-Is vs VSD

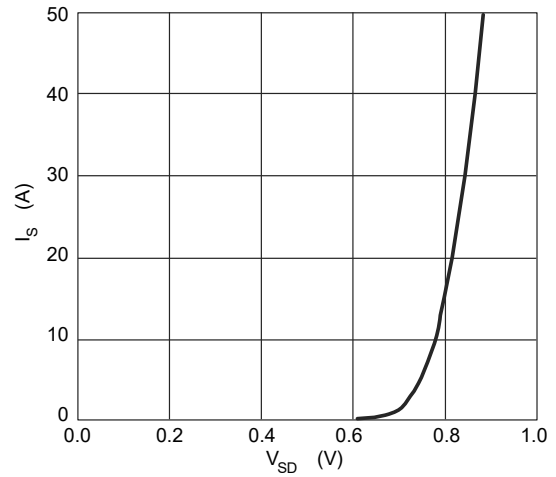


FIG. 3-Gate Charge Characteristics

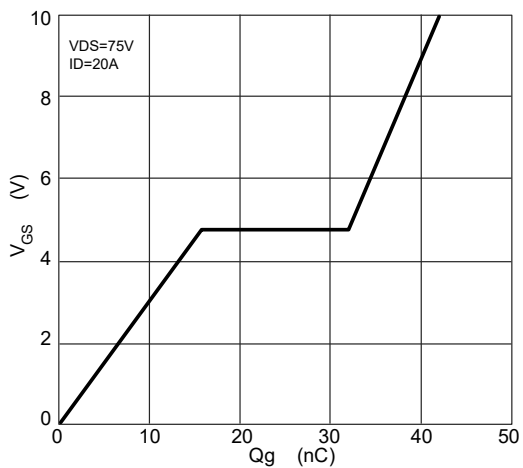


FIG. 4-RDS(on) vs VGS

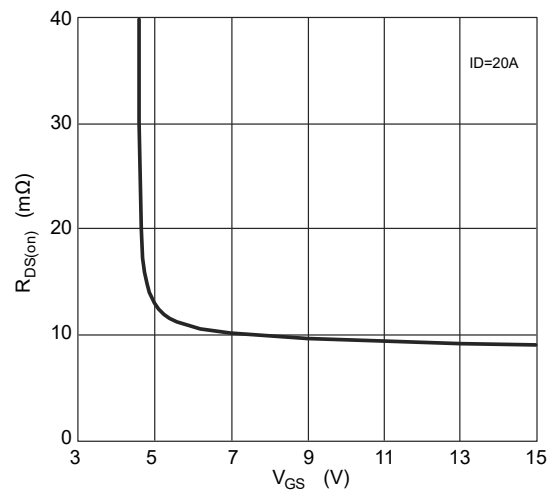


FIG. 5-RDS(on) vs ID

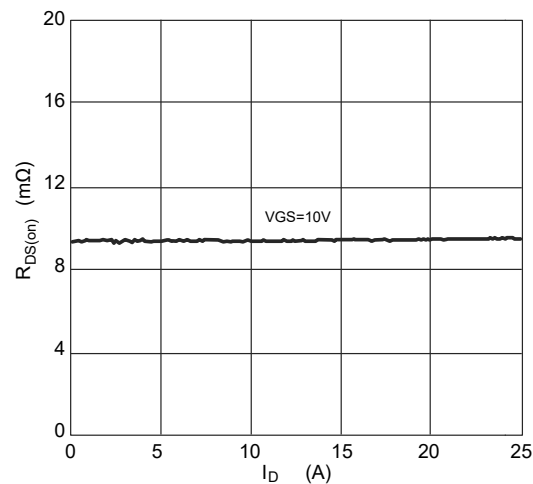
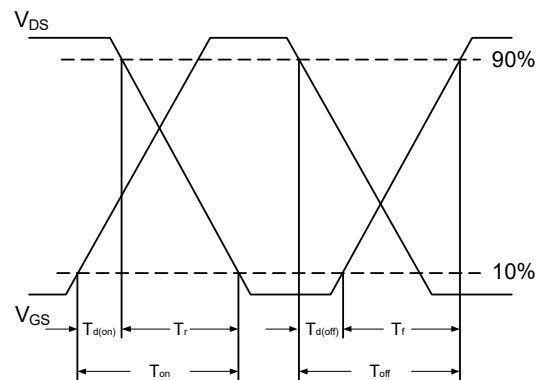


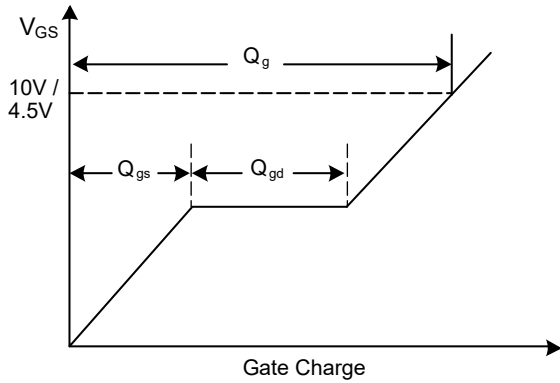
FIG. 6-Switching Time Waveform



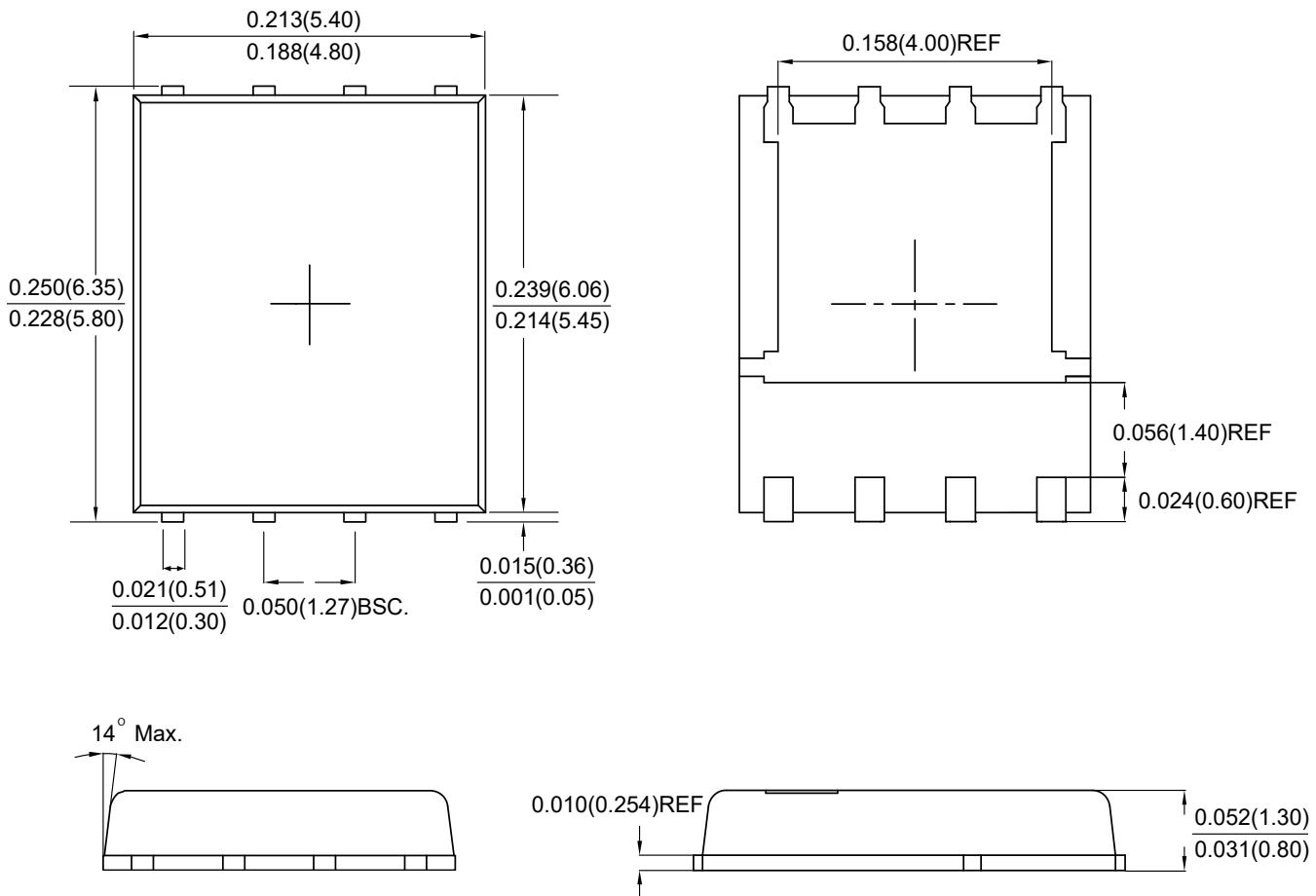


Characteristics Curves

FIG. 7-Gate Charge Waveform



Package Outline Dimensions



PPAK5X6

Dimensions in inches and (millimeters)



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